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DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER

A

SIZE

5962-88655

DAYTON, OHIO 45444

REVISION LEVEL

SHEET

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2. APPLICABLE DOCUMENTS

2.1 Government specification and standard. Unless otherwise specified, the following specification and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

REQUIREMENTS

- 3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.
- 3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
 - 3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.
 - 3.2.2 Truth table. The truth table shall be as specified on figure 2.
 - 3.2.3 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.
- 3.3 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full case operating temperature range.
- 3.4 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in 6.4 herein
- 3.5 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in 6.4. The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall state that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.
- 3.6 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.

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Test Symbol				,			Date of a second			 Und+
Test	Symbol	Conditions -55°C < T _C < +125°C Y _{CC} = 5.0 V dc ±10% unless other_specified				Group A subgroups 		Min	mits Max	Unit
High level output	V _{OH}	V _{CC} = 4.5 V, V _{IL} = 0.8 V,		OH = -30	DμA	1, 2, 3	A11	4.3		V
		VIH = 2.0 V	-	OH = -12	mA	1, 2, 3	All	2.4		٧
Low level output voltage	w level output $ V_{OL} $ $ V_{CC} = 4.5 \text{ V}$		1	OL = 300	μА	1, 2, 3	A11		0.2	Y
		VIL = 0.8 V, VIH = 2.0 V	- 1	1 _{0L} = 32	nA	1, 2, 3	A11		0.5	V
Input clamp voltage	AIK	V _{CC} = 4.5 V, I _{IN} = -18 mA				1	All		-1.2	٧
High level input IIH VCC = 5.5 V, current			AIN =	5.5 V		1, 2, 3	A11		5.0	μА
Low level input current	IIL	V _{CC} = 5.5 V, V _{IN} = GND			1, 2, 3	A11		-5.0	μ A	
High impedence output current	I OZH	V _{CC} = 5.5 V, V _{OUT} = 5.5 V			1, 2, 3	All		10	μА	
Low impedence output current	IOZL	Y _{CC} = 5.5 Y, Y _{OUT} = GND			1, 2, 3	A11		-10	μА	
Short circuit output current	108	V _{CC} = 5.5 V <u>1</u> / V _{OUT} = 0.0 V			1, 2, 3	A11	-60		mA	
Quiescent power supply current (CMOS inputs)	ICCQ	V _{IN} < 0.2 V V _{CC} = 5.5 V,	N \leq 0.2 V or V _{IN} \geq 5.3 V, C = 5.5 V, f _I = f _{CP} = 0 MHz			1, 2, 3	All		1.5	mA
Power supply current (TTL inputs high)	VI CC	V _{CC} = 5.5 V,	AIN =	3.4 V <u>2</u>	1, 2, 3	A11		2.0	mA	
Dynamic power supply I_{CCD} $V_{CC} = 5.5 \text{ V}$ $V_{IN} \geq 5.3 \text{ V}$ $\overline{DE} = \text{GND}$			or V _{IN}	s open < 0.2 V, 50% duty	cycle] <u>3</u> / 	All	 	0.4	mA/MH
Total power supply I_{CC} $\forall I_{N} \geq 5.3 \text{ V}$ current 4/ $ V_{CC} = 5.5 \text{ V}$ loutputs open one bit tog $ f_{I} = 5 \text{ MHz}$,			or VIN fcp =	< 0.2 V, TO MHz, 50% duty		1, 2, 3	ATT		5.5	mA
See footnotes at end	of table	•	·····	. <u></u>						
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Test	Symbol	Conditions -55°C < T _C < +125°C	Group A		Lin	ni ts	Unit
		$ \begin{array}{lll} -55 ^{\circ} \text{C} & < \text{T}_{\text{C}} & < +125 ^{\circ} \text{C} \\ \text{I} & \text{V}_{\text{CC}} & = 5.0 \text{ V} \text{dc} & \pm 10\% \\ \text{I} & \text{unless otherwise specified} \end{array} $	subgroups 	type	Min	Max	
Total power supply current 4/	Icc		1, 2, 3	A11		6.0	mA
Functional tests		See 4.3.1d	7,8	A11			<u> </u>
Input capacitance	CIN		4	A11		10	pF
Output capacitance	COUT	 See 4.3.1c	 4 	A11		12	l pF
Propagation delay	tpLH,	V _{CC} = 5.0 V	9, 10, 11	01	1.5	11.0	l ns
time, CP to On	tPHL	$ C_L = 50 \text{ pF}$ $ R_L = 500\Omega$		02	1.5	7.2	<u> </u>
Output enable time	tpzH,	TSee figure 3 5/	9,10,11	01	1.5	14.0	ns
	† tpzL	1	<u> </u>	02	1.5	7.5	
Output disable	tPHZ,	İ	9, 10, 11	01	1.5	8.0	ns
time	tPLZ			02	1,5	6.5	<u> </u>
Setup time	 t _s	V _{CC} = 5.0 V	9, 10, 11	01	2.5		ns
Dn to CP	-	$ C_L = 50 \text{ pF}$ $ R_L = 500\Omega$		02	2.0		
Hold time	t _h	TSee figure 3	9, 10, 11	01	2.5	 	ns
Dn to CP		! [02	1.5		<u>i</u>
CP pulse width	tpw	T 	9, 10, 11	01	7.0	<u> </u>	l l ns
(high or low)	i chm	į	,	02	6,0		T

Not more than one output should be shorted at one time, and the duration of the short circuit

where: D_H = Duty cycle for TTL inputs high N_T = Number of TTL inputs at D_H f_I = Input frequency in MHz N_I = Number of inputs at f_I f_{CP} = clock frequency in MHz

The minimum limits are guaranteed, if not tested, to the limits specified in table I.

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condition should not exceed one second.

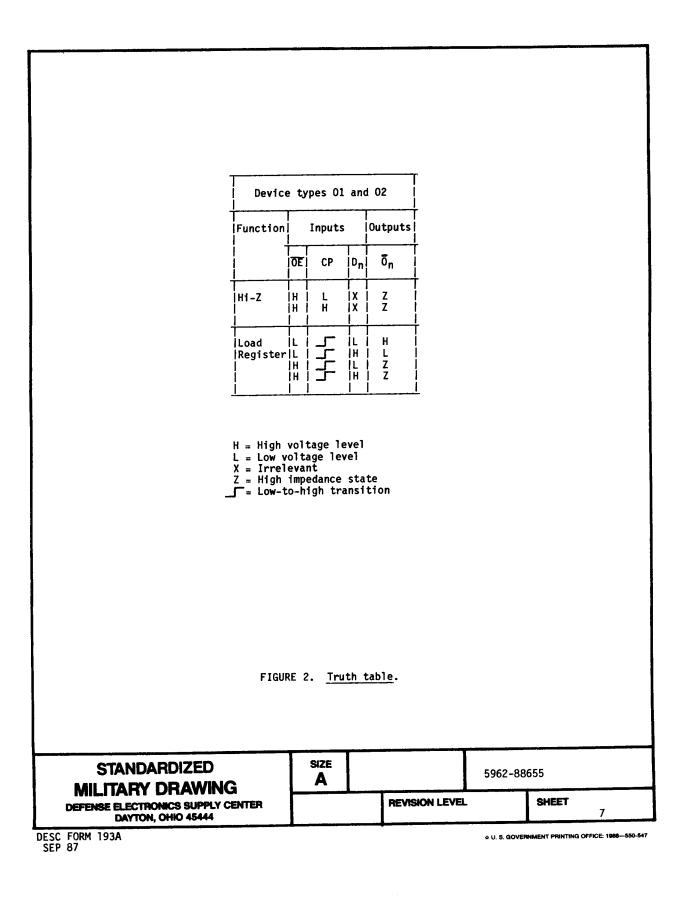
TTL driven input ($V_{IN} = 3.4 \text{ V}$); all other inputs at V_{CC} or GND.

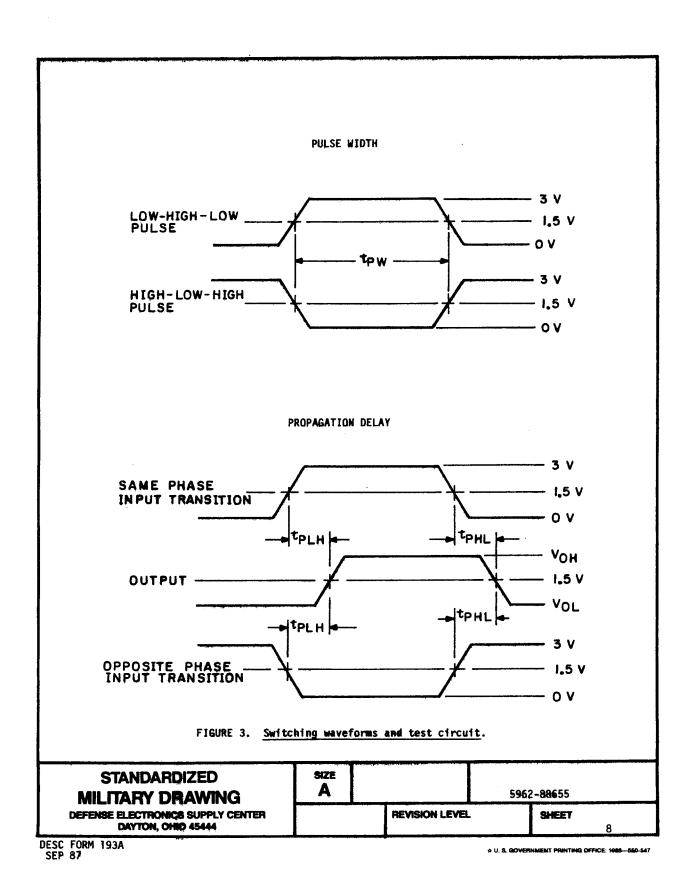
This parameter is not directly testable, but is derived for use in total power supply calculations.

 $I_{CC} = I_{CCQ} + (\Delta I_{CC} \times D_H \times N_T) + (I_{CCD}(f_I \times N_I + f_{CP}/2))$

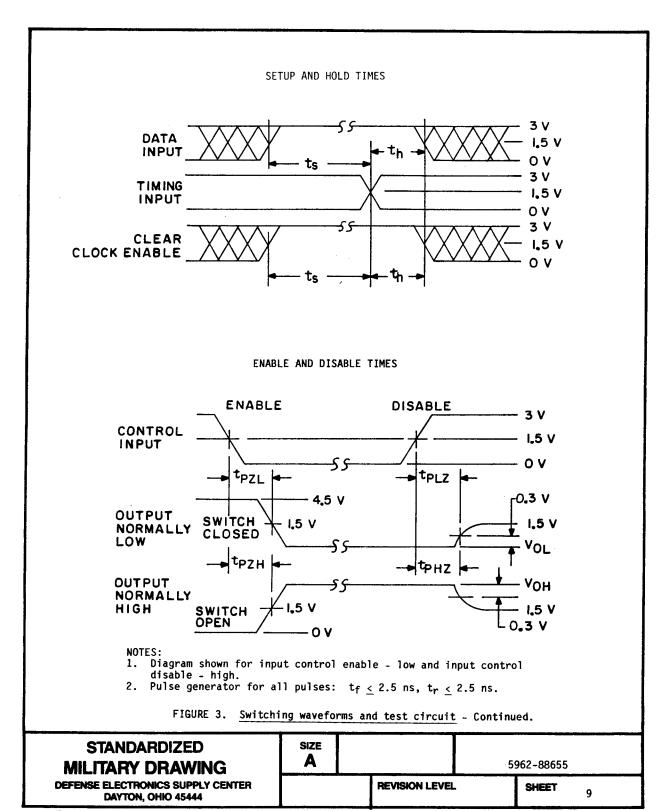
01 and 02 Device type **R**, S and 2 Package Terminal Terminal symbol number 0E 1 00 3 DO DI 5 Ō1 6 02 D2 D3 03 10 GND CP 11 12 704 13 14 D4 D5 **0**5 15 16 17 06 D6 18 D7 07 19 20 VCC FIGURE 1. Terminal connections. STANDARDIZED SIZE 5962-88655 MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, GHIR 45444 REVISION LEVEL DESC FORM 193A SEP 87

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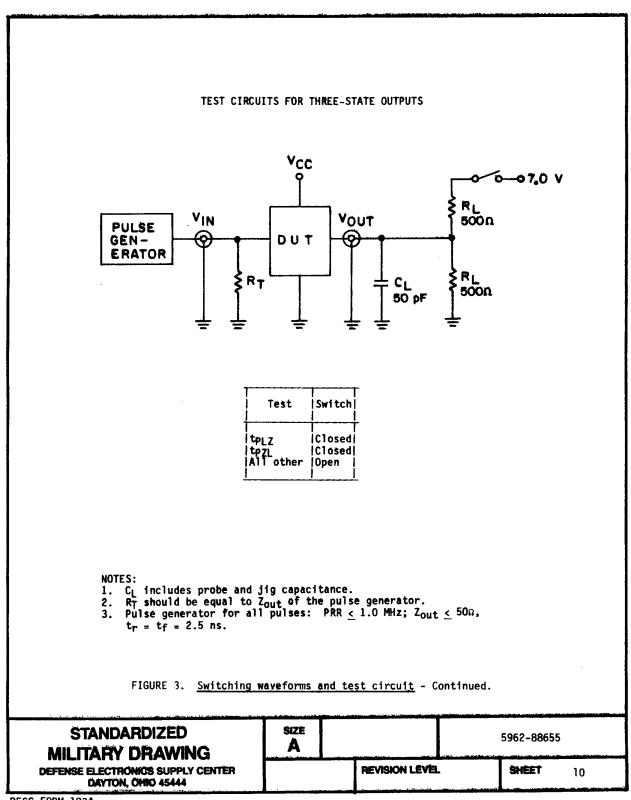




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- 3.7 Notification of change. Notification of change to DESC-ECS shall be required in accordance with MIL-STD-883 (see 3.1 herein).
- 3.8 Verification and review. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
 - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).
- 4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
 - (2) $T_A = +125^{\circ}C$, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
 - 4.3.1 Group A inspection.
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 5 and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
 - c. Subgroup 4 (C_{IN} and C_{OUT} measurements) shall be measured only for the initial test and after process or design changes which may affect capacitance. Test all applicable pins on five devices with zero failures.
 - d. Subgroups 7 and 8 tests shall verify the truth table as specified on figure 2 herein.
 - 4.3.2 Groups C and D inspections.
 - a. End-point electrical parameters shall be as specified in table II herein.
 - b. Steady-state life test conditions, method 1005 of MIL-STD-883.
 - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
 - (2) $T_A = +125^{\circ}C$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

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TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)
Interim electrical parameters (method 5004)	
Final electrical test parameters (method 5004)	1*,2,3,7,8,9, 10,11
Group A test requirements (method 5005)	 1,2,3,4,7,8, 9,10,11
Groups C and D end-point electrical parameters (method 5005)	1,2,3

* PDA applies to subgroup 1.

5. PACKAGING

- 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.
 - 6. NOTES
- 6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
- 6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone 513-296-5375.

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6.4 Approved sources of supply. Approved sources of supply are listed herein. Additional sources will be added as they become available. The vendors listed herein have agreed to this drawing and a certificate of compliance (see 3.5 herein) has been submitted to DESC-ECS.

Military drawing part number	Vendor CAGE number	Vendor similar part number <u>1</u> /
5962-8865501RX	61772 75569	IDT54FCT534DB P54PCT534DMB
5962-8865501SX	61772	IDT54FCT534EB
5962-88655012X	61772 75569	IDT54FCT534LB P54PCT534LMB
5962-8865502RX	61772 75569	IDT54FCT534ADB P54PCT534ADMB
5962-8865502SX	61772	IDT54FCT534AEB
5962-88655022X	61772 75569	IDT54FCT534ALB P54PCT534ALMB

Vendor CAGE Number

61772

Integrated Device Technology 3236 Scott Boulevard Santa Clara, CA 95052

Performance Semiconductor Corporation 610 E. Weddle Drive Sunnyvale, CA 94089

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